

**METHOD AND STRUCTURE FOR PRODUCING Z-AXIS
INTERCONNECTION ASSMEBLY OF PRINTED WIRING BOARD
ELEMENTS**

Abstract of the Disclosure

5 A method of forming a core for and forming a composite wiring board. The
core has an electrically conductive coating on at least one face of a dielectric
substrate. At least one opening is formed through the substrate extending from one
face to the other and through each conductive coating. An electrically conductive
material is dispensed in each of the openings extending through the conducting
10 coating. At least a portion of the surface of the conductive coating on one face is
removed to allow a nub of the conductive material to extend above the substrate face
and any remaining conductive material to thereby form a core that can be electrically
joined face-to-face with a second core member or other circuitized structure.